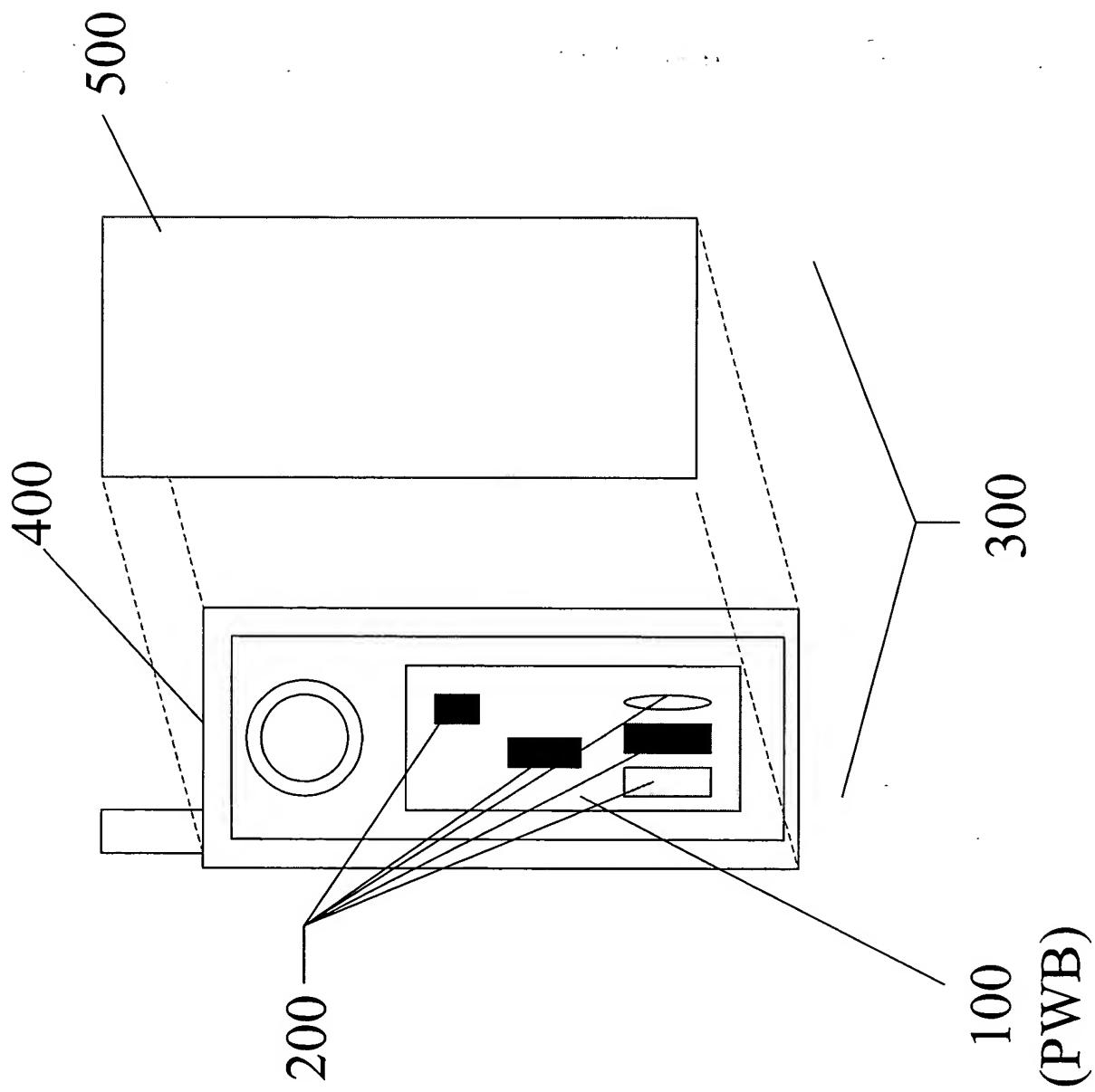
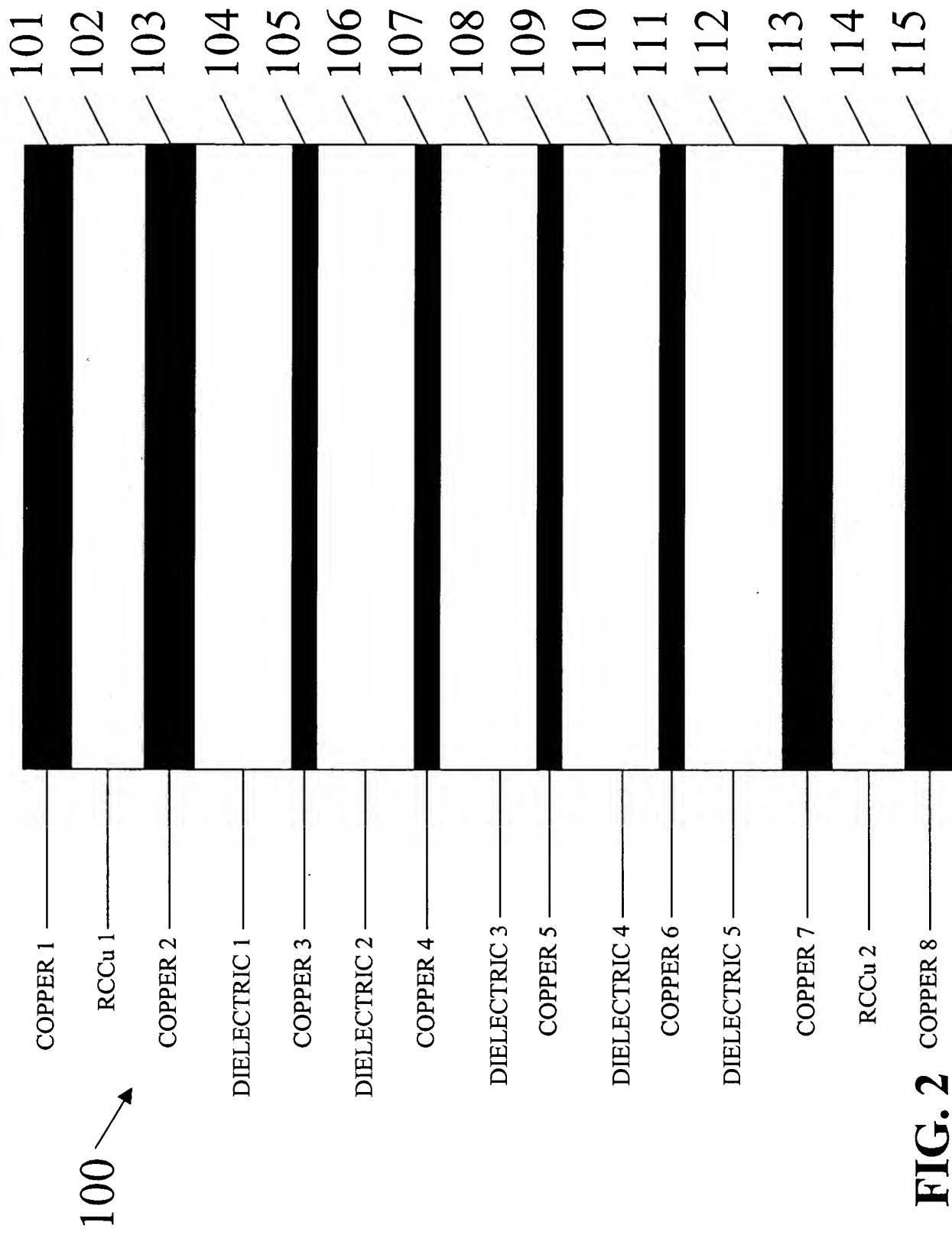


**FIG. 1**





**FIG. 2**

FIG. 3

LAYER	PWB LAYER THICKNESS/MATERIAL
COPPER 1	35 µm (+15/-10 µm)
RCCu 1	60 µm (+/-10 µm) RCCu (e.g. Matsushita R0880)
COPPER 2	35 µm (+15/-10 µm)
DIELECTRIC 1	75 µm (+/-25 µm) FR-4 (e.g. Matsushita 1766)
COPPER 3	17 µm (+2/-5 µm)
DIELECTRIC 2	75 µm (+/-25 µm) FR-4 (e.g. Matsushita 1766)
COPPER 4	17 µm (+2/-5 µm)
DIELECTRIC 3	75 µm (+/-25 µm) FR-4 (e.g. Matsushita 1766)
COPPER 5	17 µm (+2/-5 µm)
DIELECTRIC 4	75 µm (+/-25 µm) FR-4 (e.g. Matsushita 1766)
COPPER 6	17 µm (+2/-5 µm)
DIELECTRIC 5	75 µm (+/-25 µm) FR-4 (e.g. Matsushita 1766)
COPPER 7	35 µm (+15/-10 µm)
RCCu 2	60 µm (+/-10 µm) RCCu (e.g. Matsushita R0880)
COPPER 8	35 µm (+15/-10 µm)